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Information Disclosure Statement
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Form PTO-1449 (Modified)	ATTY DOCKET NO. B-3858DIV 620913-1	U.S. SERIAL NO. not yet assigned
LIST OF PATENTS AND PUBLICATIONS STATEMENT	APPLICANT(S) Daniel Yap, et al.	
	FILING DATE concurrently herewith	GROUP not yet assigned

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUB- CLASS	FILING DATE or 102(e) DATE IF APPROPRIATE
<i>[Signature]</i>	3,963,920	06/1976	Palmer	250	239	
<i>[Signature]</i>	4,358,676	11/1982	Childs, et al.	250	214R	
<i>[Signature]</i>	5,466,558	11/1995	Sasaki	430	321	
<i>[Signature]</i>	5,668,386	09/1997	Makiuchi, et al.	257	184	
<i>[Signature]</i>	6,187,515	02/2001	Tran, et al.	385	39	

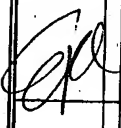

FOREIGN PATENT DOCUMENTS

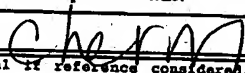
DOCUMENT NUMBER	PUBLICATION DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO
<i>[Signature]</i> 0 816 878 A2	01/1998	EP			
<i>[Signature]</i> 0 846 966 A2	06/1998	EP			
<i>[Signature]</i> 61-121014	09/1986	JP			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>[Signature]</i>	Abstract of JP 61-121014, Patent Abstracts of Japan, 1986.
<i>[Signature]</i>	Abstract of JP 03-256011, Patent Abstracts of Japan, 1991.
<i>[Signature]</i>	Balliet, L., et al., "Built-in Alignment Circuit for Fiber-Optic Silicon Optical Bench," IBM Technical Disclosure Bulletin, Vol. 24, No. 2, pp. 1158-1160 (July 1981).
<i>[Signature]</i>	Ghatak, A., et al., Introduction to Fiber Optics, Cambridge Univ. Press, pp. 221-225 (1998).
<i>[Signature]</i>	Imler, W.R., "Precision Flip-Chip Solder Bump Interconnects for Optical Packaging," IEEE Transactions on Components, Hybrids, and Manufacturing Technology, Vol. 15, No. 6 (Dec. 1992), pp. 997-981.

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EXAMINER	DATE CONSIDERED
	4/30/04

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.